

Appl. No.: 10/695,026  
Amendment dated December 20, 2006  
Response to Office Action mailed September 21, 2006

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**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claims 1-24 (cancelled)

Claim 25 (currently amended): The semiconductor wafer package device according to claim 24 ~~46~~ wherein each said device is a digital micromirror device.

Claim 26 (currently amended): The semiconductor wafer package device according to claim 24 ~~46~~ wherein said micromechanical components are micromirrors.

Claims 27-30 (cancelled)

Claim 31 (currently amended): The semiconductor wafer package device according to claim 24 ~~48~~ wherein said solder is selected from a group consisting of lead/tin, indium, tin/indium, tin/silver, tin/bismuth, solder paste, and solder-coated spheres.

Claims 32-35 (cancelled)

Claims 36-44 (withdrawn)

Claims 45 (cancelled)

Claim 46 (new): A semiconductor wafer comprising:

- a plurality of devices, each device including of an integrated circuit and a plurality of micromechanical components configured in a plane in a central portion of a surface of said device, and
- a plurality of terminals disposed in peripheral portions of said surface of said device serving as electrical inputs/outputs of said integrated circuit and said micromechanical components,

wherein said semiconductor wafer is coated with a protective material.

Claim 47 (new): The semiconductor wafer of claim 46 wherein said protective material is partially removed to expose said plurality of terminals of each device.

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Claim 48 (new): The semiconductor wafer of claim 47 further comprising solder electrically connected to said plurality of terminals in the peripheral portions of said surface of each said device.

Claim 49 (new): The semiconductor wafer of claim 48 wherein said solder comprises solder balls respectively located on said exposed terminals.